

ABSTRACT

A universal snap-fit system for interconnecting multiple circuit boards in a stacked relationship is provided. The system allows circuit boards to be stacked with a minimum of assembly time. In addition, the system allows circuit boards of varying thicknesses to be stacked, without requiring the provision of system components in a multitude of sizes. The provided system also allows more than two circuit boards to be interconnected to one another in a stacked relationship without requiring multiple sets of attachment holes in interior circuit boards. In addition, more than two circuit boards can be stacked quickly and easily.

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